

selective conductive via fills, as needed. While a via interconnect system is described in the preferred embodiment above, as would be known by one ordinarily skilled in the art given this disclosure, other similar processing is possible with the invention. For example, an insulator may be placed against those vias that are not to be conductive thru vias as shown in Figure 3B.

The invention allows for quicker build times for new products and a reduction of punched sheet part numbers, which results in larger batch size and reduced costs. It is ideal for gang punching of a product. Minimal screening masks would be required.

While the invention has been described in terms of preferred embodiments, those skilled in the art will recognize that the invention can be practiced with modification within the spirit and scope of the appended claims.